PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Raymond John Donohoe	08/12/2008
Krishna Vepa	11/12/2008
Paul V. Miller	11/04/2008
Ronald Rayandayan	10/20/2008
Hong Wang	08/14/2008
Christophe Maleville	09/15/2008

RECEIVING PARTY DATA

Name:	Applied Materials, Inc.
Street Address:	3050 Bowers Avenue
City:	Santa Clara
State/Country:	CALIFORNIA
Postal Code:	95054

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12177752

CH $40.00 12177752

CORRESPONDENCE DATA

Fax Number: (650)326-2422

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 6503262400
Email: lamirelez@townsend.com
Correspondent Name: Townsend & Townsend & Crew LLP
Address Line 1: Two Embarcadero Center, 8th Floor
Address Line 4: San Francisco, CALIFORNIA 94111

ATTORNEY DOCKET NUMBER:	016301-080810US
NAME OF SUBMITTER:	Craig C. Largent

Total Attachments: 12
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source=2008_11_12_ASSGMT_016301-080810US#page2.tif
source=2008_11_12_ASSGMT_016301-080810US#page3.tif
source=2008_11_12_ASSGMT_016301-080810US#page4.tif
source=2008_11_12_ASSGMT_016301-080810US#page5.tif
source=2008_11_12_ASSGMT_016301-080810US#page6.tif
source=2008_11_12_ASSGMT_016301-080810US#page7.tif
source=2008_11_12_ASSGMT_016301-080810US#page8.tif
source=2008_11_12_ASSGMT_016301-080810US#page9.tif
source=2008_11_12_ASSGMT_016301-080810US#page10.tif
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Attorney Docket No.: A09197C01/T08010
AMAT No.: 009197C01 USA/AGS/SPARES/HMM
TTC No.: 016301-080810US

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses
of Inventors:

1)	Raymond John Donohoe RD. Alexander-Herzen Strasse 19 Dresden 01109 Germany	2)	Krishan Vepa 44 Lily Court Danville, CA 94506 United States
3)	Paul V. Miller 10816 Undavista Drive Cupertino, CA 95014 United States	4)	Ronald Rayandayan 2262 Eric Court, No. 4 Union City, CA 94587 United States
5)	Hong Wang 10355 Cherry Tree Lane Cupertino, CA 95014 United States	6)	Christophe Maleville S.O.I. Tec Silicon On Insulator Technologies S.A. Chemin des Franques, Parc Technologique des Fontaines Bernin38190 France

(hereinafter referred to as Assignors), have invented a certain invention entitled:

EDGE REMOVAL OF SILICON-ON-INSULATOR TRANSFER WAFER

for which application for Letters Patent in the United States was filed on July 22, 2008, under Application No. 12/177,752, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division,

substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1) 12th AUGUST, 2008 R. J. Donohoe
Raymond John Donohoe

2) ______________, 2008 ______________
Krishan Vepa

3) ______________, 2008 ______________
Paul V. Miller

4) ______________, 2008 ______________
Ronald Rayandayan

5) ______________, 2008 ______________
Hong Wang

6) ______________, 2008 ______________
Christophe Maleville

Attorney Docket No.: A09197C01/T08010
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TTC No.: 016301-080810US

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Names and Addresses
of Inventors:

1)	Raymond John Donohoe Bishofsweg 54 Dresden01099 Germany	2)	Krishna ~~Krishan~~ Vepa ~~44 Lily Court~~ 1664 Hope Dr #1024 ~~Danville, CA 94506~~ Santa Clara, CA 95054 United States
3)	Paul V. Miller 10816 Undavista Drive Cupertino, CA 95014 United States	4)	Ronald Rayandayan 2262 Eric Court, No. 4 Union City, CA 94587 United States
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1) ____________________, 2008 ____________________
Raymond John Donohoe

2) Nov 12, 2008 ____________________
~~Krishan~~ Vepa
Krishna KV

3) ____________________, 2008 ____________________
Paul V. Miller

4) ____________________, 2008 ____________________
Ronald Rayandayan

5) ____________________, 2008 ____________________
Hong Wang

6) ____________________, 2008 ____________________
Christophe Maleville

Attorney Docket No.: A09197C01/T08010
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1) ______________________, 2008 ______________________
Raymond John Donohoe

2) ______________________, 2008 ______________________
Krishan Vepa

3) 11/4, 2008 ______________________
Paul V. Miller

4) ______________________, 2008 ______________________
Ronald Rayandayan

5) ______________________, 2008 ______________________
Hong Wang

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Christophe Maleville

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Raymond John Donohoe

2) ____________________, 2008 ____________________
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3) ____________________, 2008 ____________________
Paul V. Miller

4) OCT- 20, 2008 Ronald R. Rayandayan
Ronald Rayandayan

5) ____________________, 2008 ____________________
Hong Wang

6) ____________________, 2008 ____________________
Christophe Maleville

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Raymond John Donohoe

2) ____________________, 2008 ____________________
Krishan Vepa

3) ____________________, 2008 ____________________
Paul V. Miller

4) ____________________, 2008 ____________________
Ronald Rayandayan

5) Aug. 14, 2008, 2008 ____________________
Hong Wang

6) ~~Aug. 14, 2008~~ HW, 2008 ____________________
Christophe Maleville

Attorney Docket No.: A09197C01/T08010
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4) ______________________, 2008 ______________________
Ronald Rayandayan

5) ______________________, 2008 ______________________
Hong Wang

6) 15 Septembre, 2008 ______________________
Christophe Maleville

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